

ABSTRACT OF THE DISCLOSURE

5 A semiconductor substrate device comprises a
first semiconductor substrate including a concave-convex
surface and a second semiconductor substrate having an
insulating film on a surface thereof. The first
semiconductor substrate and the second semiconductor
substrate are brought together so that the surface of the
first semiconductor substrate and the insulating film
10 provided on the surface of the second semiconductor
substrate contact each other to form a cavity in the
semiconductor substrate device.